



Thermal Conductive Gel series

【Thermal Gap filler】

DATA SHEET



- Product picture -

Thermally conductive gel is a thermal interface material with single-component. The material has some stress-strain value superior than the ultra-soft silicone sheet. It can be automatically dispensed and coated. It is the best heat dissipation solution when multiple chips share a radiator and structures.

FEATURES:

- High thermal conductivity, low thermal resistance
- Small Young modulus
- No silicone oil and pollution
- Excellent machinability

APPLICATIONS:

- Semiconductors and radiators
- Power resistor and power base
- Temperature regulator and Assembly surface
- Thermoelectric cooling devices
- CPU and GPU

The series of products are accord with standards of RoHS and HALOGEN.

STORAGE TEMPERATURE:

- 25°C(6 mouths)
- 4°C(12 mouths)

STORAGE CONDITIONS:

- In order to ensure that the products maintain the quality, it should be kept in low temperature with dry and sealed environment or container.
- During the storage period, make sure that the container is sealed to protect electrical performance from external contaminants.

PACKING SPECIFICATIONS:

- 30cc/50cc/300cc

PROPERTIES

Items	Parameter		Unit	Test Method
	HTG-300	HTG-500		
Appearance	Pink pasty substance	Dark grey pasty substance	-	Visual
Density	3.2(±0.5)	3.1(±0.5)	g/cm ³	ASTM D 792
Volatilize Point (200°C, 24h)	≤200	≤200	ppm	GB269-85
50% Instantaneous compressive stress	<10	<10	Psi	GB/T 7757-2009
50% Static compressive stress	<1	<1	Psi	GB/T 7757-2009
Adhesive force	<15	<15	Psi	-
Operating Temperature	-50~150	-50~150	°C	-

THERMAL CHARACTERISTIC

Thermal Conductivity	3.2(±0.25)	5.0(±0.5)	W/m·K	ASTM D 5470
Thermal Resistance	≤0.08(@20Psi)	≤0.04(@20Psi)	°Cin ² /W	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown Voltage	≥8(@1mm)	≥2.5(@1mm)	KV	ASTM D 149
Volume Resistivity	≥1.0*10 ¹²	≥1.0*10 ¹⁰	Ω.cm	ASTM D 257

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